

# 5A/6A Peak Current, 500kHz Synchronous Step-Up PWM Converter

# HT79171/HT79181

Revision: V1.10 Date: May 24, 2024

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# **Table of Contents**

Features	3
Applications	3
General Description	3
Typical Application Circuit	4
Block Diagram	
Pin Assignment	5
Pin Description	5
Absolute Maximum Ratings	5
Recommended Operating Ratings	
Electrical Characteristics	
Typical Performance Characteristics	
Functional Description	
Linear Charge Mode – LCM	
Soft Start	
Setting the Output Voltage	23
Setting the Over Current Threshold using an External Resistor	23
Output Disconnect During Shutdown	24
Protections	24
Component Selection Guide	25
Inductor	26
Input Capacitor	26
Output Capacitor	26
Input Fiter	26
Output Filter	26
Layout Consideration Guide	27
Thermal Considerations	28
Package Information	29
8-pin SOP-EP (150mil) Outline Dimensions	
FC Type 10-pin QFN (2mm×2mm) Outline Dimensions	31



#### **Features**

- Input Voltage from 2.2V to 5.0V
- Adjustable Output Voltage from 2.6V to 5.5V
- Guaranteed Continuous Output Capability: 2A/3A(HT79171/HT79181) with  $V_{OUT}=5.0V$  and  $V_{IN}=3.3V$
- Internal Ultra-Low Power Switches:  $25m\Omega/45m\Omega$  (HT79171) and  $20m\Omega/40m\Omega$  (HT79181) at 5.0V output
- Up to 95% Efficiency
- Fixed PWM Switching Frequency: 500kHz
- Precision Feedback Reference Voltage: 0.6V (±1.5%)
- Ultra-Low Shutdown Current < 1µA
- Load Disconnect (Vout=0V) and Fast Discharging to Ground during Shutdown
- Embedded Loop Frequency Compensation
- Programmable OCP Threshold via External Resistor, R<sub>CS</sub>
- Extensive Protection Functions: Soft-Start when Power-On/Enable (SS), Input Under Voltage Lockout (UVLO), Over Current Limit Protection (OCP), Over Temperature Protection (OTP), Output Over Voltage Protection (OVP) and Output Short Protection without Heating (OSP)
- Package Types: 10-pin QFN and 8-pin SOP-EP

#### **Applications**

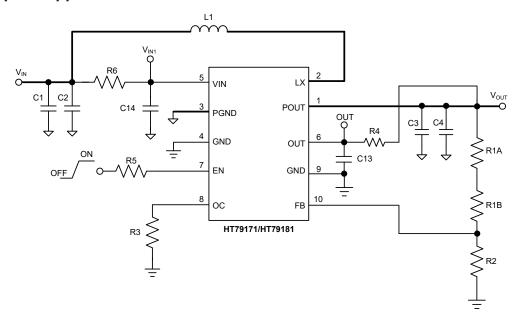
- · All Single Cell Li or Dual Cell Batteries
- · Portable Equipment

#### **General Description**

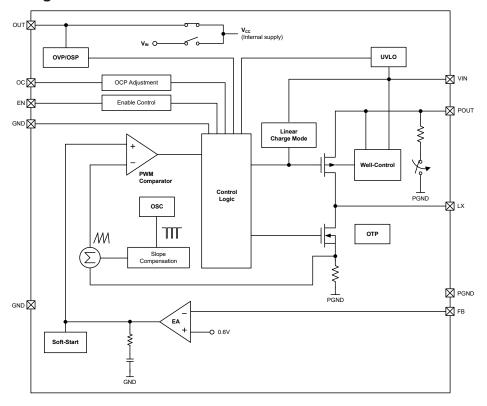
The HT79171 and HT79181 are synchronous step-up DC-DC converters. With a wide input range from 2.2V to 5.0V, the devices are suitable for portable li-battery based applications such as power banks. The devices are able to provide a continuous 2A/3A current output due to their ultra-low integrated  $R_{\rm DSONs}$  which is  $25 m \Omega/45 m \Omega$  and  $20 m \Omega/40 m \Omega$  for the main FET and synchronous FET respectively. This greatly improves the efficiency and reduces the junction/case temperature. Due to a high operation switching frequency of 500kHz, the devices require only a small number of external components while still have the advantages of low output voltage ripple. The embedded loop frequency compensation circuitry simplifies the system design and reduces the required number of external components.



# **Typical Application Circuit**



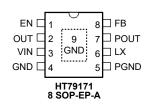
# **Block Diagram**

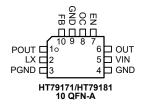


Rev. 1.10 4 May 24, 2024



# **Pin Assignment**





# **Pin Description**

Pin	Pir	No.	Time	Description	
Name	10QFN	8SOP-EP	Type	Description	
POUT	1	7	0	Power output Decouple this pin by connecting a capacitor with a minimum value of 22µF for noise immunity.	
LX	2	6	0	Inductor connection	
PGND	3	5	G	Power ground	
GND	4	4	G	Signal ground	
VIN	5	3	Р	Power supply input	
OUT	6	2	0	Signal output. Decouple this pin by connecting a capacitor with a minimum value of 1µF for noise immunity.	
EN	7	1	I	Enable control – high active	
ОС	8	_	I	Adjust current limit via an external resistor connected to ground	
GND	9	_	I	Remains connected to GND	
FB	10	8	I	Error amplifier inverting input	
EP	_	9	G	Exposed pad. Connect to GND	

Note: The 8-pin SOP-EP package is only available for the HT79171.

# **Absolute Maximum Ratings**

Parameter	Value	Unit		
VIN Pin Input Voltage Range		-0.3 to +6	V	
EN Pin Input Voltage Range		-0.3 to (V <sub>OUT</sub> +0.3)	V	
Other Pin Voltage Range		+6	V	
Power Dissipation		+2.5	W	
Maximum Junction Temperature		+150	°C	
Storage Temperature Range	-60 to +150	°C		
Lead Temperature – soldering 10 seconds		+260	°C	
TCD Cussontibility	Human Body Model	2000	V	
ESD Susceptibility	Machine Model	200	V	
10QFN		50	°C/\\/	
Junction-to-Ambient Thermal Resistance, θ <sub>JA</sub> 8SOP-EP		125	°C/W	
lunation to Coop Thormal Popietones O	10QFN	10	°C/\\/	
Junction-to-Case Thermal Resistance, θ <sub>JC</sub>	8SOP-EP	25	°C/W	



## **Recommended Operating Ratings**

Parameter	Value	Unit
VIN Pin Input Voltage Range	2.2 to 5.0	V
POUT and OUT Pin Output Voltage Range	2.6 to 5.5	V
EN Pin Input Voltage Range	0 to (V <sub>OUT</sub> +0.3)	V
Other Pin Voltage Range	0 to 5.5	V
Junction Temperature Range	-40 to +125	°C
Operating Temperature Range	-40 to +85	°C

Note that Absolute Maximum Ratings indicate limitations beyond which damage to the device may occur. Recommended Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specified performance limits.

#### **Electrical Characteristics**

 $V_{\text{IN}}\text{=}2.2\text{V},\,V_{\text{OUT}}\text{=}5\text{V},\,I_{\text{OUT}}\text{=}0.5\text{A}$  and  $T_{\text{A}}\text{=}25^{\circ}\text{C},\,\text{unless otherwise specified}.$ 

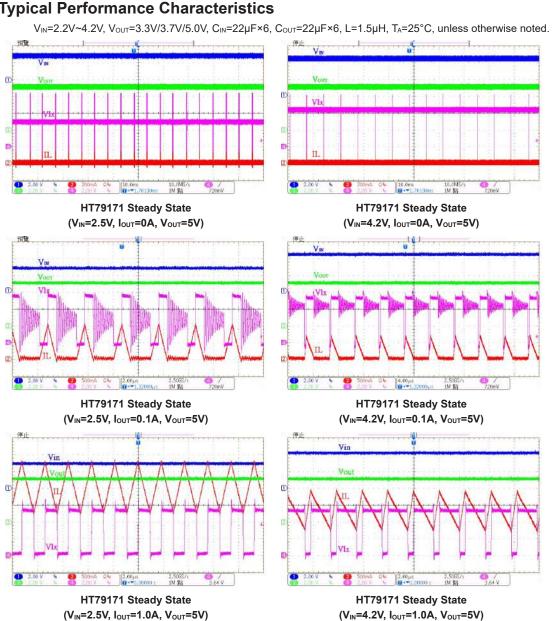
Symbol	Parameter		Test Condition	Min.	Тур.	Max.	Unit
Supply V	oltage						
V <sub>IN</sub>	Input Voltage Range		_	2.2	_	5.0	V
lα	Quiescent Current – no switching	V <sub>IN</sub> V <sub>OUT</sub>	V <sub>EN</sub> =2.2V, V <sub>FB</sub> =0.66V, V <sub>OUT</sub> =5V, I <sub>OUT</sub> =0A	_	30 65	45 80	μΑ
I <sub>SHD</sub>	Shutdown Current		V <sub>EN</sub> =0V, measure I(V <sub>IN</sub> )	_	0.1	1.0	μA
Boost Co	pnverter						
Vout	Output Voltage Range		_	2.6	_	5.5	V
f <sub>sw</sub>	Switching Frequency		V <sub>FB</sub> =0.54V	400	500	600	kHz
t <sub>OFF(min)</sub>	Minimum OFF Time		_	_	100	150	ns
t <sub>ON(min)</sub>	Minimum ON Time		_	_	180	_	ns
D	Laur Oide Main EET		V <sub>OUT</sub> =5V, HT79171	_	25	_	mΩ
$R_{ON(N)}$	Low Side Main FET		V <sub>OUT</sub> =5V, HT79181	_	20	_	mΩ
D	Synchronous FET		V <sub>OUT</sub> =5V, HT79171	_	45	_	mΩ
$R_{ON(P)}$			V <sub>OUT</sub> =5V, HT79181	_	40	_	mΩ
I(V <sub>LX</sub> )	Low Side Main FET Leakage Curr	ent	V <sub>EN</sub> =0V, V <sub>IN</sub> =V <sub>LX</sub> =5.5V	_	0.1	1.0	μA
I(V <sub>оит</sub> )	Synchronous FET Leakage Current		V <sub>EN</sub> =V <sub>IN</sub> =5.5V,V <sub>FB</sub> =0.66V, V <sub>LX</sub> =0V, V <sub>OUT</sub> =5.5V	_	0.1	1.0	μΑ
V <sub>FB</sub>	Feedback Voltage		V <sub>IN</sub> =2.2V, V <sub>OUT</sub> =5V, I <sub>OUT</sub> =0A	0.591	0.600	0.609	V
I <sub>FB</sub>	Feedback Leakage Current		V <sub>FB</sub> =5V	_	0.1	0.5	μA
R <sub>EN</sub>	EN Pull Down Resistance		_	_	3	_	МΩ
V <sub>IH</sub>	EN High Voltage Threshold		2.2V≤V <sub>IN</sub> ≤5.5V	_	_	1.5	V
VIL	EN Low Voltage Threshold		2.2V≤V <sub>IN</sub> ≤5.5V	0.4	_	_	V
R <sub>DIS</sub>	Discharge Resistance to GND		V <sub>EN</sub> =0V	_	1.8	_	kΩ
Protection	ons						
$V_{\text{UVLO+}}$	Input Supply Turn ON Level		_	_	_	2.2	V
$V_{\text{UVLO\_HYS}}$	UVLO Hysteresis		_	_	0.2	_	V
tss	Soft-Start Time		V <sub>IN</sub> =3.3V, I <sub>OUT</sub> =3.0A	_	1.75	_	ms
lasa	Over Current Protection Threshold	4	HT79171, OC pin is floating	5.0	_	_	Α
IOCP	Over Guiterit Frotection Threshold		HT79181, OC pin is floating	6.0	_	_	
V <sub>OVP</sub>	Output Over Voltage Threshold		_	5.55	5.60	6.50	V
V <sub>OVP_HYS</sub>	OVP Release Hysteresis		_	_	0.3	_	V

Rev. 1.10 6 May 24, 2024

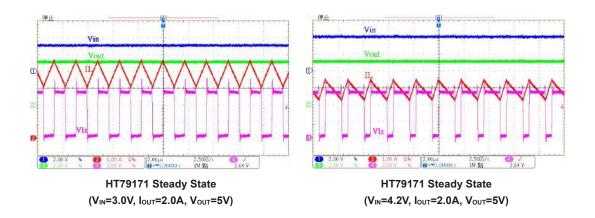


Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
V <sub>OSP_TR</sub>	Output Short Circuit Trigger Threshold	2.2V≤V <sub>IN</sub> ≤5.5V, measure at V <sub>OUT</sub>	_	0.87×V <sub>IN</sub>	_	V
V <sub>OCP_RE</sub>	Output Short Circuit Release Threshold	2.2V≤V <sub>IN</sub> ≤5.5V, measure at V <sub>OUT</sub>	_	0.93×V <sub>IN</sub>	_	V
t <sub>OSP(RE)</sub>	OSP Re-Detection Time	2.2≤V <sub>IN</sub> ≤5.5V, V <sub>OUT</sub> =0.85×V <sub>IN</sub>	_	120	_	ms
t <sub>OSP</sub>	OSP Decision Time	2.2V≤V <sub>IN</sub> ≤5.5V, V <sub>OUT</sub> =0.85×V <sub>IN</sub>	_	3	_	ms
Тотр	Thermal Shutdown Threshold	_	_	150	_	°C
T <sub>OTP(RE)</sub>	Thermal Recovery Temperature	_	_	125		°C

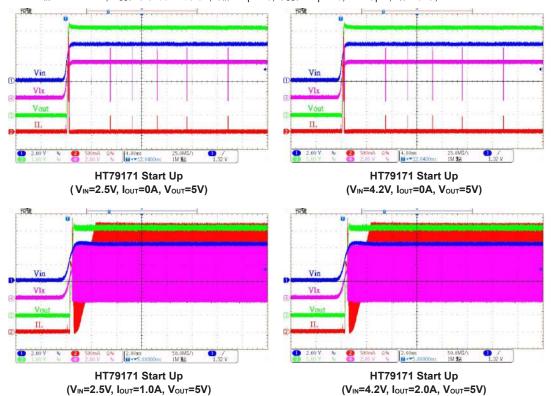
## **Typical Performance Characteristics**





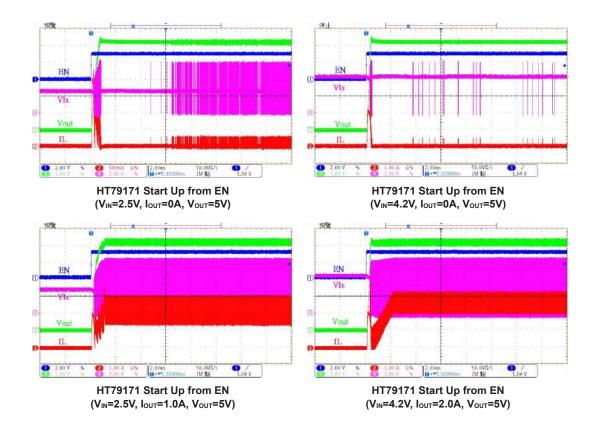






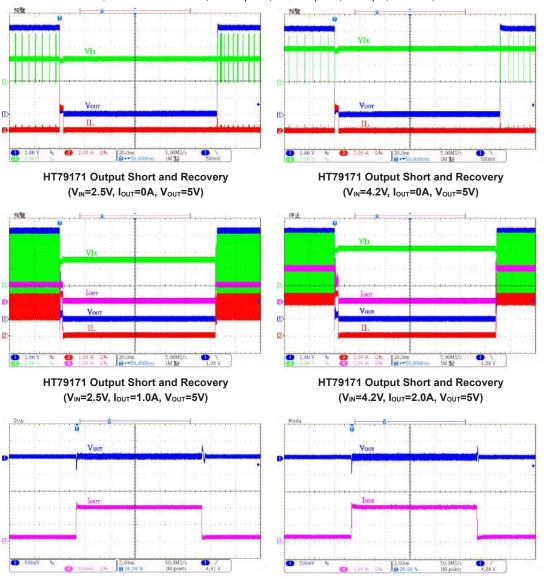
Rev. 1.10 8 May 24, 2024







 $V_{\text{IN}} = 2.2 \text{V} \sim 4.2 \text{V}, \ V_{\text{OUT}} = 3.3 \text{V} / 3.7 \text{V} / 5.0 \text{V}, \ C_{\text{IN}} = 22 \mu F \times 6, \ C_{\text{OUT}} = 22 \mu F \times 6, \ L = 1.5 \mu H, \ T_{\text{A}} = 25 ^{\circ} \text{C}, \ unless \ otherwise \ noted.$ 



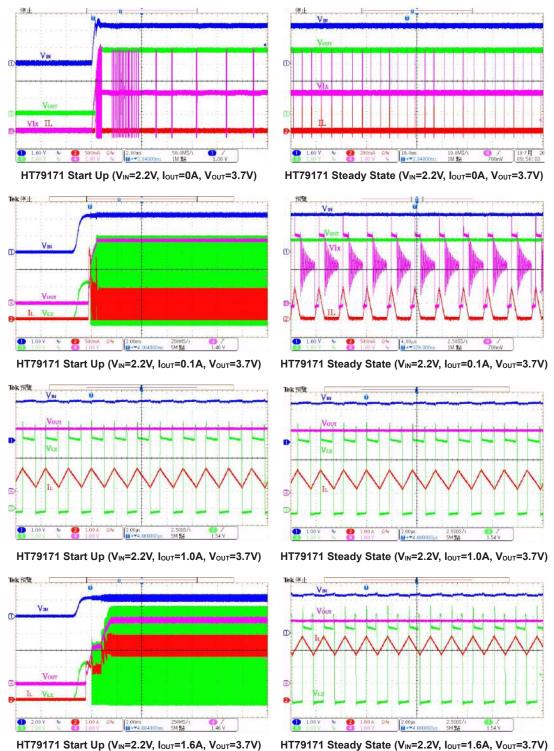
HT79171 Load Transient ( $V_{IN}$ =2.5V,  $I_{OUT}$ =0.1A->1.0A,  $V_{OUT}$ =5V)

HT79171 Load Transient ( $V_{IN}$ =4.2V,  $I_{OUT}$ =0.2A->2.0A,  $V_{OUT}$ =5V)

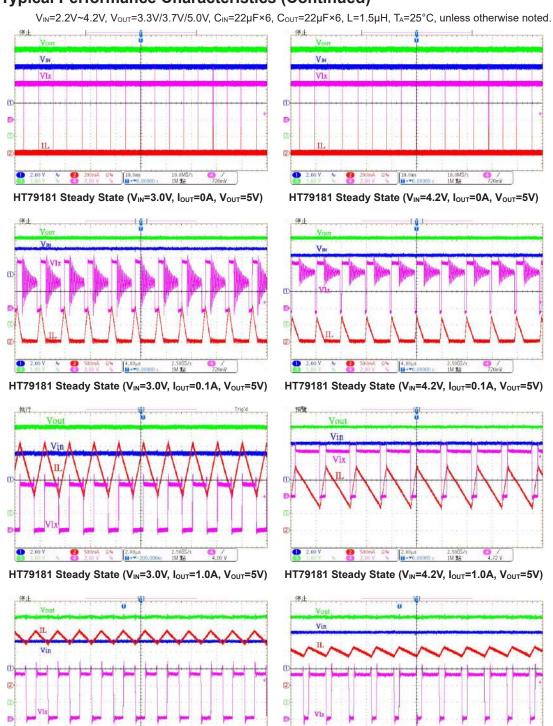
Rev. 1.10 10 May 24, 2024



 $V_{\text{IN}} = 2.2 \text{V} - 4.2 \text{V}, \ V_{\text{OUT}} = 3.3 \text{V}/3.7 \text{V}/5.0 \text{V}, \ C_{\text{IN}} = 22 \mu \text{F} \times 6, \ C_{\text{OUT}} = 22 \mu \text{F} \times 6, \ L = 1.5 \mu \text{H}, \ T_{\text{A}} = 25^{\circ} \text{C}, \ unless otherwise noted}.$ 







HT79181 Steady State (V<sub>IN</sub>=3.0V, I<sub>OUT</sub>=3.0A, V<sub>OUT</sub>=5V)

HT79181 Steady State (V<sub>IN</sub>=4.2V, I<sub>OUT</sub>=3.0A, V<sub>OUT</sub>=5V)



 $V_{\text{IN}} = 2.2 \text{V} \sim 4.2 \text{V}, \ V_{\text{OUT}} = 3.3 \text{V} / 3.7 \text{V} / 5.0 \text{V}, \ C_{\text{IN}} = 22 \mu F \times 6, \ C_{\text{OUT}} = 22 \mu F \times 6, \ L = 1.5 \mu H, \ T_{\text{A}} = 25 ^{\circ} \text{C}, \ unless \ otherwise \ noted.$ Vin Vlx Vout HT79181 Start Up HT79181 Start Up  $(V_{IN}=2.5V, t_r=1ms, I_{OUT}=0A, V_{OUT}=5V)$ ( $V_{IN}$ =4.2V,  $t_r$ =1ms,  $I_{OUT}$ =0A,  $V_{OUT}$ =5V) HT79181 Start Up HT79181 Start Up  $(V_{IN}=2.5V, t_r=1ms, I_{OUT}=1.5A, V_{OUT}=5V)$  $(V_{IN}=4.2V, t_r=1ms, I_{OUT}=3.0A, V_{OUT}=5V)$ EN Vlx П HT79181 Start Up from EN HT79181 Start Up from EN (V<sub>IN</sub>=2.5V, I<sub>OUT</sub>=0A, V<sub>OUT</sub>=5V) ( $V_{IN}$ =4.2V,  $I_{OUT}$ =0A,  $V_{OUT}$ =5V) HT79181 Start Up from EN HT79181 Start Up from EN  $(V_{IN}=2.5V, I_{OUT}=1.5A, V_{OUT}=5V)$  $(V_{IN}=4.2V, I_{OUT}=3.0A, V_{OUT}=5V)$ 

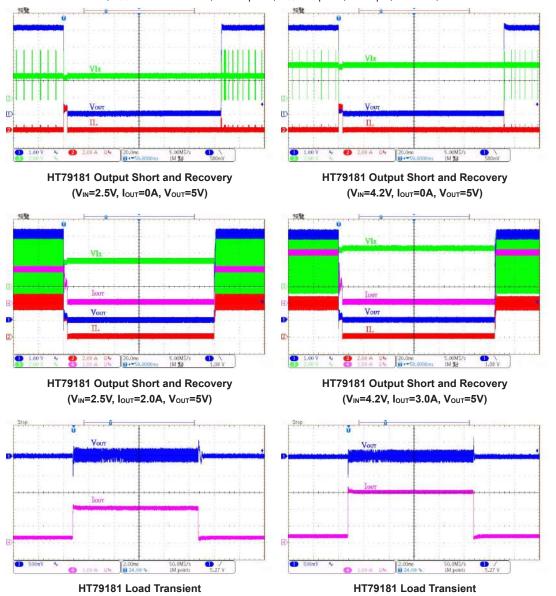
 $(V_{IN}=4.2V, I_{OUT}=0.3A->3.0A, V_{OUT}=5V)$ 



## **Typical Performance Characteristics (Continued)**

 $(V_{IN}=2.5V, I_{OUT}=0.2A->2.0A, V_{OUT}=5V)$ 

 $V_{\text{IN}} = 2.2 \text{V} \sim 4.2 \text{V}, \ V_{\text{OUT}} = 3.3 \text{V} / 3.7 \text{V} / 5.0 \text{V}, \ C_{\text{IN}} = 22 \mu F \times 6, \ C_{\text{OUT}} = 22 \mu F \times 6, \ L = 1.5 \mu H, \ T_{\text{A}} = 25 ^{\circ} \text{C}, \ unless \ otherwise \ noted.$ 



Rev. 1.10 14 May 24, 2024



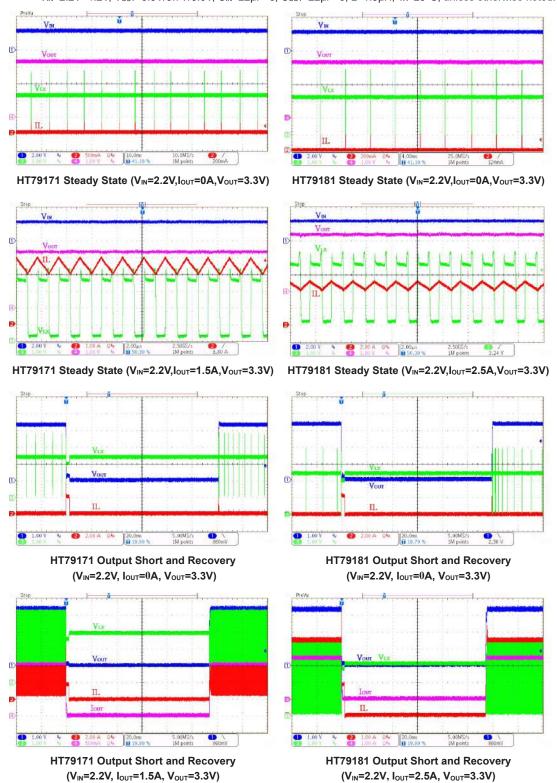
 $V_{\text{IN}} = 2.2 \text{V} \sim 4.2 \text{V}, \ V_{\text{OUT}} = 3.3 \text{V} / 3.7 \text{V} / 5.0 \text{V}, \ C_{\text{IN}} = 22 \mu \text{F} \times 6, \ C_{\text{OUT}} = 22 \mu \text{F} \times 6, \ L = 1.5 \mu \text{H}, \ T_{\text{A}} = 25^{\circ} \text{C}, \ \text{unless otherwise noted}.$ 100A Q4 HT79181 Start Up (V<sub>IN</sub>=2.2V, I<sub>OUT</sub>=0A, V<sub>OUT</sub>=3.7V) HT79181 Steady State (VIN=2.2V, IOUT=0A, VOUT=3.7V) HT79181 Start Up (V<sub>IN</sub>=2.2V, I<sub>OUT</sub>=0.1A, V<sub>OUT</sub>=3.7V) HT79181 Steady State (VIN=2.2V, IOUT=0.1A, VOUT=3.7V) HT79181 Start Up from EN HT79181 Steady State  $(V_{IN}=2.2V, I_{OUT}=1.0A, V_{OUT}=3.7V)$  $(V_{IN}=2.2V, I_{OUT}=1.0A, V_{OUT}=3.7V)$ EN HT79181 Start Up from EN HT79181 Steady State

 $(V_{IN}=2.2V, I_{OUT}=2.5A, V_{OUT}=3.7V)$ 

 $(V_{IN}=2.2V, I_{OUT}=1.5A, V_{OUT}=3.7V)$ 



V<sub>IN</sub>=2.2V~4.2V, V<sub>OUT</sub>=3.3V/3.7V/5.0V, C<sub>IN</sub>=22µF×6, C<sub>OUT</sub>=22µF×6, L=1.5µH, T<sub>A</sub>=25°C, unless otherwise noted.

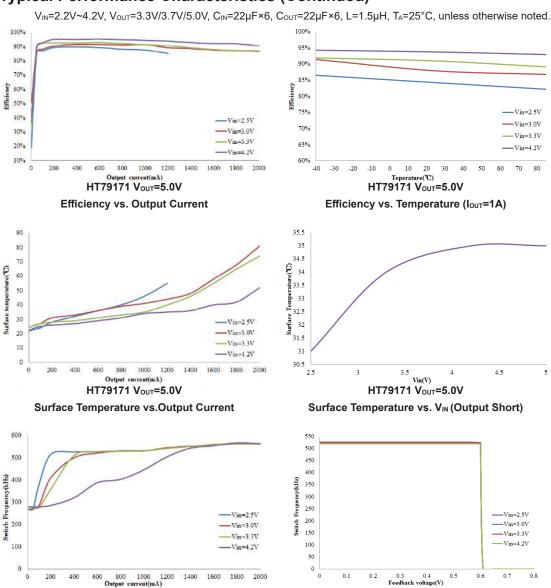


Rev. 1.10 16 May 24, 2024

HT79171 Vout=5.0V fsw vs. Output Current



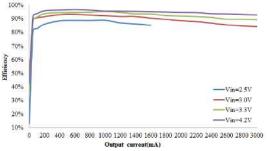
#### **Typical Performance Characteristics (Continued)**

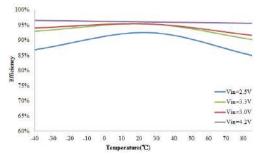


HT79171 Vout=5.0V fsw vs. Feedback Voltage



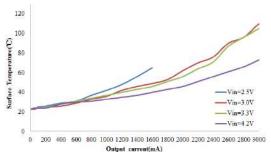
V<sub>IN</sub>=2.2V~4.2V, V<sub>OUT</sub>=3.3V/3.7V/5.0V, C<sub>IN</sub>=22µF×6, C<sub>OUT</sub>=22µF×6, L=1.5µH, T<sub>A</sub>=25°C, unless otherwise noted.

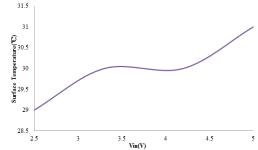




HT79181 Vout=5.0V Efficiency vs. Output Current

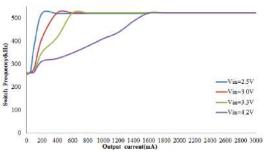
HT79181 Vout=5.0V Efficiency vs. Temperature (Iout=1A)

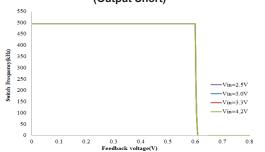




HT79181 Surface Temperature vs. Output Current

HT79181 V<sub>OUT</sub>=5.0V Surface Temperature vs. V<sub>IN</sub> (Output Short)





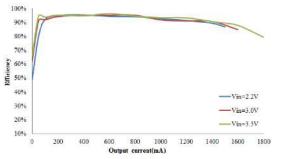
HT79181 Vout=5.0V fsw vs. Output Current

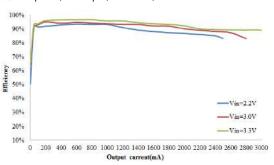
HT79181 Vout=5.0V fsw vs. Feedback Voltage

Rev. 1.10 18 May 24, 2024



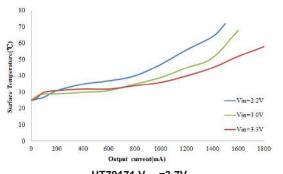
 $V_{\text{IN}} = 2.2 \text{V} \sim 4.2 \text{V}, \ V_{\text{OUT}} = 3.3 \text{V} / 3.7 \text{V} / 5.0 \text{V}, \ C_{\text{IN}} = 22 \mu F \times 6, \ C_{\text{OUT}} = 22 \mu F \times 6, \ L = 1.5 \mu H, \ T_{\text{A}} = 25 ^{\circ} \text{C}, \ unless \ otherwise \ noted.$ 

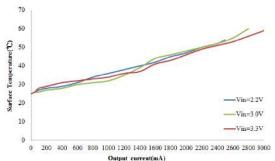




HT79171 V<sub>OUT</sub>=3.7V Efficiency vs. Output Current

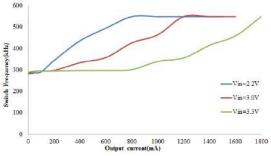
HT79181 V<sub>OUT</sub>=3.7V Efficiency vs. Output Current

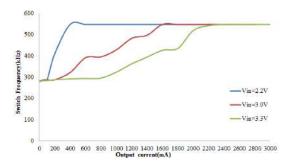




HT79171 V<sub>OUT</sub>=3.7V
Surface Temperature vs. Output Current

HT79181 V<sub>OUT</sub>=3.7V Surface Temperature vs. Output Current



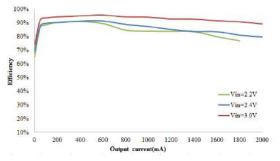


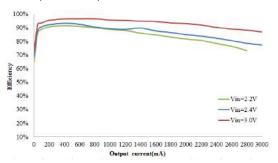
HT79171 Vout=3.7V fsw vs. Output Current

HT79181 V<sub>OUT</sub>=3.7V f<sub>SW</sub> vs. Output Current



 $V_{\text{IN}} = 2.2 \text{V} \sim 4.2 \text{V}, \ V_{\text{OUT}} = 3.3 \text{V} / 3.7 \text{V} / 5.0 \text{V}, \ C_{\text{IN}} = 22 \mu F \times 6, \ C_{\text{OUT}} = 22 \mu F \times 6, \ L = 1.5 \mu H, \ T_{\text{A}} = 25 ^{\circ} \text{C}, \ unless \ otherwise \ noted.$ 

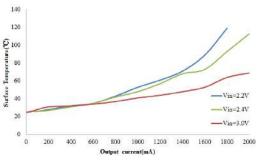




HT79171 Vout=3.3V

Efficiency vs. Output Current

HT79181 Vout=3.3V





**Efficiency vs. Output Current** 160 140 (2) 120 100 80 60 40 20

HT79171 Vout=3.3V

HT79181 Vout=3.3V

200 400 600 800 1000 1200 1400 1600 1800 2000 2200 2400 2600 2800 3000

---Vin=3.0V

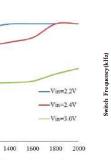


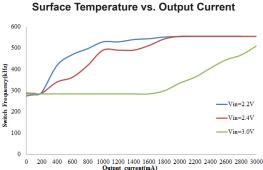
Switch Frequency (kHz) 300 200

100

400

200





HT79171 Vout=3.3V

600 800 1000 1200 Output current(mA)

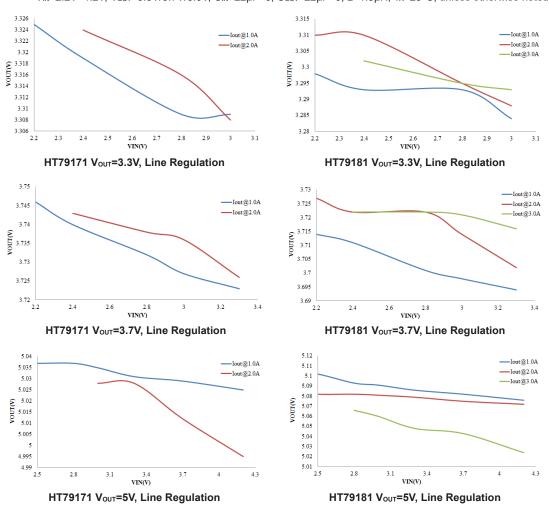
HT79181 Vout=3.3V

fsw vs. Output Current

fsw vs. Output Current

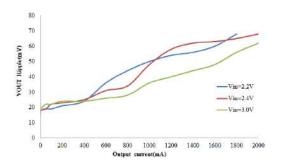


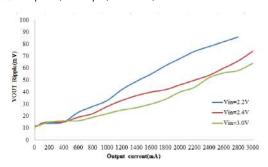
 $V_{\text{IN}} = 2.2 \text{V} \sim 4.2 \text{V}, \ V_{\text{OUT}} = 3.3 \text{V} / 3.7 \text{V} / 5.0 \text{V}, \ C_{\text{IN}} = 22 \mu F \times 6, \ C_{\text{OUT}} = 22 \mu F \times 6, \ L = 1.5 \mu H, \ T_{\text{A}} = 25 ^{\circ} \text{C}, \ unless \ otherwise \ noted.$ 



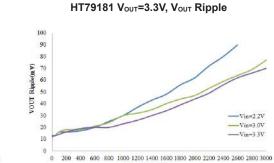


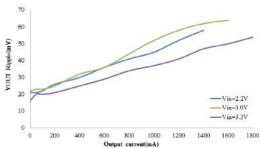
 $V_{\text{IN}} = 2.2 \text{V} \sim 4.2 \text{V}, \ V_{\text{OUT}} = 3.3 \text{V} / 3.7 \text{V} / 5.0 \text{V}, \ C_{\text{IN}} = 22 \mu F \times 6, \ C_{\text{OUT}} = 22 \mu F \times 6, \ L = 1.5 \mu H, \ T_{\text{A}} = 25 ^{\circ} \text{C}, \ unless \ otherwise \ noted.$ 

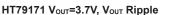




HT79171 Vout=3.3V, Vout Ripple

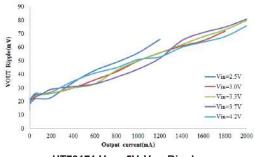




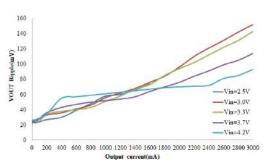


HT79181 Vout=3.7V, Vout Ripple

-Vin=3.0V



HT79171 Vout=5V, Vout Ripple



HT79181 Vout=5V, Vout Ripple

Rev. 1.10 22 May 24, 2024



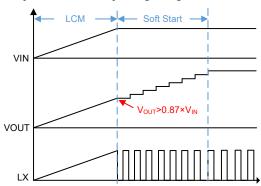
#### **Functional Description**

#### Linear Charge Mode - LCM

The HT79171/79181 will enter the Linear Charge Mode (LCM) when  $V_{OUT}$ <0.87× $V_{IN}$ . In this mode, the high side MOSFET is conducted and charges the output capacitor. The device will exit the linear charge mode once  $V_{OUT}$ =0.87× $V_{IN}$ .

#### **Soft Start**

The HT79171 and HT79181 devices include a soft start function to prevent inrush current and overshoot situations from occurring during the power-on period. The soft start function is executed when  $V_{OUT}>0.87\times V_{IN}$ . The time duration is 1.75ms ( $V_{IN}=3.3V@3.0A$ ) to steady output voltage. In the light load condition, the output will reach the operating voltage in advance and finish the soft start process.



#### Setting the Output Voltage

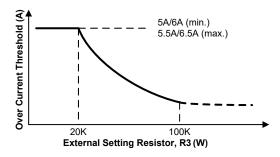
As shown in the Typical Application Circuit, the external resistor divider defines the output voltage. The feedback resistor, R1, together with the internal compensation capacitor, defines the feedback loop bandwidth. The output voltage,  $V_{\text{OUT}}$ , is calculated by the following equation:

$$V_{OUT}=0.6V\times(R1A+R1B+R2)/R2$$
 (V)

#### Setting the Over Current Threshold using an External Resistor

By default, the HT79171/HT79181's maximum peak current passing through the main FET is restricted to 5A/6A when the OC pin is floating. When a resistor is connected and whose value is between  $20k\Omega$  and  $100k\Omega$ , the current limit will be set within a range from 5A/6A to 1A/1.2A for the HT79171/HT79181 respectively. Do not connect any capacitor to this pin. The over current trip point can be calculated according to the equation:

$$I_{OCP}$$
=100000/R3(A) ...... HT79171  
 $I_{OCP}$ =120000/R3(A) ...... HT79181



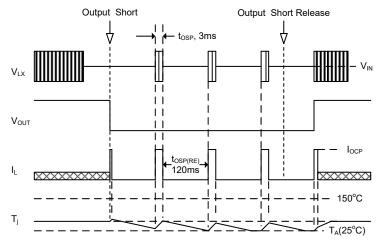


#### **Output Disconnect During Shutdown**

The HT79171 and HT79181 devices also support a shutdown mode which reduces the supply current to approximately 0.1mA and separates the output node ( $V_{OUT}$ ) and input node ( $V_{IN}$ ) by reversing the intrinsic diode of the synchronous FET. Therefore, the output node could be fully connected to the ground terminal (0V) without resulting in any current leakage. A  $1k\Omega$  discharge path to ground is also applied to reduce the time taken for  $V_{OUT}$  to fall to 0V.

#### **Protections**

The HT79171 and HT79181 both have dedicated protection circuits running during normal operation to protect the IC. The linear charge mode is implemented to limit the inrush current during the power-on period. The Over Current Protection (OCP) sets a maximum current value and is illustrated below. The Over Temperature Protection (OTP) turns off the power device when the die temperature reaches an excessive level. The Under Voltage Lock-Out comparator (UVLO) protects the power device during power supply startup and shutdown periods to prevent the devices from operating at voltages which are less than the minimum input voltage. The devices restrict their maximum output voltage to VOVP to avoid damage to the internal components. Once the output voltage exceeds the specified voltage, the devices will switch off both the main FET and the synchronous FET. When an output short fault occurs, the devices will turn off for 120ms and then restart the boost converter for 3ms, cycle by cycle (OSP). The following figure shows what happens when an output short fault happens. Once the OSP, OTP, OVP and UVLO situations are released, the devices will be restarted.



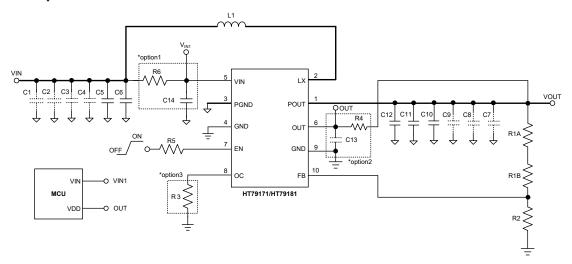
Protection Type	Protection Entry Condition	V <sub>OUT</sub> During Protection Period	Protection Release Condition
UVLO	V <sub>IN</sub> <2.0V	V <sub>OUT</sub> =0V	V <sub>IN</sub> >2.2V
OCP	I <sub>LX</sub> >5A (for HT79171) I <sub>LX</sub> >6A (for HT79181)	Decreasing along with I <sub>OUT</sub> increasing	I <sub>LX</sub> <5A (for HT79171) I <sub>LX</sub> <6A (for HT79181)
OVP	V <sub>OUT</sub> >V <sub>OVP</sub>	Clamp $V_{\text{OUT}}$ between $V_{\text{OVP}}$ and $V_{\text{OVP-HYS}}$	Fault is removed
OTP	Tj>150°C	V <sub>OUT</sub> =0V	Tj<125°C
OSP	V <sub>OUT</sub> is short connected to GND	V <sub>OUT</sub> =0V	Short fault is released

**Protection Function Conditions** 

Rev. 1.10 24 May 24, 2024



## **Component Selection Guide**



Reference	Package	Description	Mfgr.
R3	SMD 0603	N.C.	_
R4	SMD 0603	0Ω±1%	Liker Corp.
R5	SMD 0603	10kΩ±1%	Liker Corp.
R6	SMD 0603	0Ω±1%	Liker Corp.

Reference	Package	Description	Part Number	Mfgr.
C5	SMD 0805	Ceramic, 22µF,10V	CM0805Y5V226M6R3AT	QSEC
C6	SMD 0805	Ceramic, 22µF,10V	CM0805Y5V226M6R3AT	QSEC
C10	SMD 0805	Ceramic, 22µF,10V	CM0805Y5V226M6R3AT	QSEC
C11	SMD 0805	Ceramic, 22µF,10V	CM0805Y5V226M6R3AT	QSEC
C12	SMD 0603	Ceramic, 0.1µF,10V	0603B104K500CT	WALSIN
C13	SMD 0603	N.C.	_	_
C14	SMD 0603	Ceramic, 1nF,10V	GRM188R71H103KA01D	Murata
L1	SMD 6030	ZPWM-6030M-1R5M	_	ZenithTek

V <sub>OUT</sub>	Package	R1A	R1B	R2
2.5	SMD 0603	240kΩ±1%	20kΩ±1%	82kΩ±1%
3.0	SMD 0603	300kΩ±1%	0Ω±1%	75kΩ±1%
3.3	SMD 0603	330kΩ±1%	7.5k±1%	75kΩ±1%
3.71	SMD 0603	300kΩ±1%	22kΩ±1%	62kΩ±1%
4.0	SMD 0603	430kΩ±1%	0Ω±1%	75kΩ±1%
5.1	SMD 0603	560kΩ±1%	0Ω±1%	75kΩ±1%

<sup>\*</sup> option1: Add this circuit when the load carrying capacity of the input power is limited. R6 and C14 are recommended to be  $1k\Omega$  and  $10\mu F$  respectively.

<sup>\*</sup> option2: Add the R4 and C13 filter if the application requires lower  $V_{\text{OUT}}$  ripple. R4 and C13 are recommended to be  $100\Omega$  and  $10\mu F$  respectively.

<sup>\*</sup> option3: R3 resistance can be adjusted according to the required current limit.

#### Inductor

In most applications, it is recommended to use a 1.5µH or higher inductance to maintain a low output ripple voltage. Inductance DCR, inductor core loss and efficiency loss caused by the switching frequency will influence the overall efficiency. A low DCR with a value less than  $50m\Omega$  is suggested to reduce efficiency loss. The inductance could be calculated using the following formula:  $\frac{V_{IN}}{V_{OUT}-V_{IN}}$ 

$$L1 = (\frac{V_{IN}}{V_{OUT}})^2 \times (\frac{V_{OUT} - V_{IN}}{I_{RIPPLE} \times f_{SW}})$$

 $I_{RIPPLE} = I_{OUTMAX} \times 40\%$ ,  $I_{OUTMAX}$  stands for the maximum load current;  $f_{SW}$  stands for the switching frequency; IRIPPLE stands for the ripple current. The saturation current is suggested to be at least 10A.

#### **Input Capacitor**

Multiple capacitors are required between the VIN and GND pins to reduce the input power ripple noise. Use ceramic capacitors with X5R or X7R dielectrics for their low ESRs and small temperature coefficients. For most applications, 22µF×2 will be a suitable value. It is recommended to use the 22µF, 0805,10V capacitors. If the load carrying capacity of the input power is limited, more capacitors and an additional input flter circuit are recommended to add.

#### **Output Capacitor**

To reduce the output voltage ripple noise, multiple capacitors are required between the VOUT and GND pins. Their selection is determined by the steady state and transient state response. Use ceramic capacitors with X5R or X7R dielectrics for their low ESRs and small temperature coefficients. For most applications,  $22\mu F \times 2$  will be a suitable value. It is recommended to use the 22μF, 0805,10V capacitors. To avoid undesired OVP function triggered by V<sub>OUT</sub>=5.5V or when the application requires lower output ripple, it is recommended to add more output capacitors and an output filter.

#### **Input Fiter**

If the load carrying capacity of the input power is limited, such as dry battery, solar battery etc., the IC UVLO protection may be mistakenly triggered because the battery voltage is dropped to a lower level by the internal large resistance and heavy load of the battery. It is suggested to add a low-pass filter (R6 and C14) before the input to avoid this situation. If the system has an MCU to detect V<sub>IN</sub>, a more stable input power can be detected from the filtered VIN1 point. The recommended values are  $R6=1k\Omega$  and  $C14=10\mu F$ .

#### **Output Filter**

Considering that the system usually needs a low ripple voltage to supply power for the MCU ADC and AVDD, etc. a low-pass filter (R4 and C13) can be added at the OUT. In this way, the main load is supplied by VOUT while the low consumption loads requiring low ripple, such as MCU ADC and AVDD, are supplied by OUT. The recommended values are R4=100 $\Omega$  and C13=10 $\mu$ F.

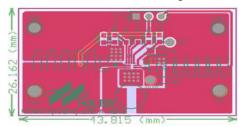
Rev. 1.10 26 May 24, 2024



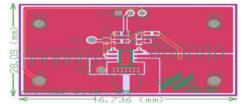
#### **Layout Consideration Guide**

To achieve the best efficiency and to reduce noise, there are some important points to note regarding the PCB layout.

- 1. The C<sub>OUT</sub> capacitors should be placed as close to the POUT and PGND pins as possible.
- 2. The feedback resistors R1A, R1B and R2 should not be close to the LX pin to avoid noise interference. It is suggested to pull the feedback from the farthest COUT in parallel.
- 3. Considering the large current problem, the trace width between VIN and LX is suggested to be wider than 3mm.
- 4. GND is the grounding for the internal control signal and PGND is the grounding of large current. Gather the GND signals and connect them with PGND, then lay a large area of copper and add vias to improve heat dissipation.
- 5. It is recommended to place R4 and C13 close to the OUT and place R6 and C14 close to the VIN.
- 6. L1 should be placed as close to the IC as possible. It is recommended to lay a large area of copper on the PCB board for the VIN and VOUT signals.



10-pin QFN PCB Layout Example



8-pin SOP-EP PCB Layout Example

Rev. 1.10 27 May 24, 2024

#### **Thermal Considerations**

For continuous operation, do not exceed the absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow and the allowed difference between the junction and ambient temperatures. The maximum power dissipation can be calculated by the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A)/\theta_{JA}$$
 (W)

Where  $T_{J(MAX)}$  is the maximum junction temperature,  $T_A$  is the ambient temperature and  $\theta_{JA}$  is the junction to ambient thermal resistance.

The recommended operating conditions specify a maximum junction temperature of 125°C. The junction to ambient thermal resistance,  $\theta_{JA}$ , is dependent upon the layout. On a standard JEDEC 51-7 four-layer thermal test board, the thermal resistance,  $\theta_{JA}$ , of the 10-pin QFN package is 50°C /W and 8SOP-EP package is 125°C/W.. The maximum power dissipation at  $T_A$ =25°C can be calculated by the following formula:

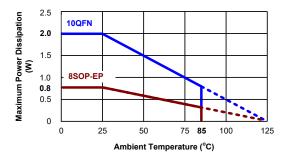
10QFN:

$$P_{D(MAX)}=(4125^{\circ}C-25^{\circ}C)/(50^{\circ}C/W)=2.0W$$

8SOP-EP:

$$P_{D(MAX)} = (125^{\circ}C - 25^{\circ}C)/(125^{\circ}C/W) = 0.8W$$

For a fixed  $T_{J(MAX)}$  of 125°C, the maximum power dissipation depends on the operating ambient temperature and the package's thermal resistance,  $\theta_{JA}$ . The de-rating curve below shows the effect of rising ambient temperature on the maximum recommended power dissipation.



Rev. 1.10 28 May 24, 2024



## **Package Information**

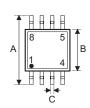
Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the <u>Holtek website</u> for the latest version of the <u>Package/Carton Information</u>.

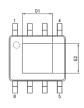
Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- The Operation Instruction of Packing Materials
- Carton information

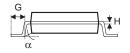


## 8-pin SOP-EP (150mil) Outline Dimensions









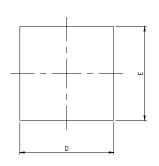
Comb al		Dimensions in inch			
Symbol	Min.	Nom.	Max.		
A		0.236 BSC			
В		0.154 BSC			
С	0.012	_	0.020		
C'	0.193 BSC				
D	_	_	0.069		
D1	0.076	_	0.118		
E		0.050 BSC			
E2	0.075	_	0.101		
F	0.000	_	0.006		
G	0.016	_	0.050		
Н	0.004	_	0.010		
α	0°	_	8°		

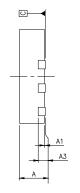
Combal		Dimensions in mm	
Symbol	Min.	Nom.	Max.
A		6.00 BSC	
В		3.90 BSC	
С	0.31	_	0.51
C'	4.90 BSC		
D	_	_	1.75
D1	1.94	_	3.00
E		1.27 BSC	
E2	1.90	_	2.56
F	0.00	_	0.15
G	0.40	_	1.27
Н	0.10	_	0.25
α	0°	_	8°

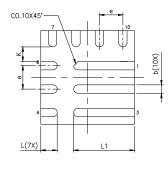
Rev. 1.10 30 May 24, 2024



# FC Type 10-pin QFN (2mm×2mm) Outline Dimensions







Symbol	Dimensions in inch			
	Min.	Nom.	Max.	
A	0.020	0.022	0.024	
A1	0.000	0.001	0.002	
A3	0.006 REF			
b	0.006	0.008	0.010	
D	0.079 BSC			
E	0.079 BSC			
е	0.020 BSC			
L	0.010	0.014	0.018	
L1	0.047	0.051	0.055	
K	0.008	0.012	0.016	

Symbol	Dimensions in mm			
	Min.	Nom.	Max.	
A	0.50	0.55	0.60	
A1	0.00	0.02	0.05	
A3	0.15 REF			
b	0.15	0.20	0.25	
D	2.00 BSC			
E	2.00 BSC			
е	0.50 BSC			
L	0.25	0.35	0.45	
L1	1.20	1.30	1.40	
K	0.20	0.30	0.40	



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Rev. 1.10 32 May 24, 2024